TSMC and MediaTek Extend Collaboration on Ultra-Low Power Technology to Capture the Emerging IoT Market

Hsinchu, Taiwan, R.O.C. – March 15, 2016 – TSMC (TWSE: 2330, NYSE: TSM) and MediaTek (TWSE: 2454) today announced their commitment to a long-term partnership to continue developing innovative products for Internet of Things (IoT) and wearable products with TSMC's industry-leading and most comprehensive ultra-low power (ULP) technology platform. In this platform, TSMC offers multiple processes to provide significant power reduction benefits for IoT and wearable products and a comprehensive design ecosystem to accelerate time-to-market for customers.

In January, TSMC and MediaTek achieved their first product milestone on this platform by launching MediaTek's MT2523 chipset for fitness smart watches. Built on TSMC's 55nm ULP technology, MT2523 is the world's first system-in-package (SiP) solution to offer GPS, dual-mode Bluetooth Low Energy, and a MIPI-supported high-resolution mobile screen.

"We are pleased to continue the success of MT2523 and collaborate with TSMC in developing market leading IoT/wearable products using ULP technologies," said JC Hsu, MediaTek's Corporate Vice President and General Manager of IoT business unit.

"TSMC's offerings of 55-nanometer ultra-low power (55ULP), 40ULP, 28HPC+, and 16FFC are ideally suited for a variety of smart and power-efficient applications in the IoT and wearable device markets," said Dr. BJ Woo, TSMC's Vice President, Business Development. "Collaborating with MediaTek, an innovator with expertise in bringing the best solution to the end customers, drives the advancement of TSMC ULP technologies that can enable the best and most competitive IoT product solutions to the world."

About TSMC

TSMC is the world's largest dedicated semiconductor foundry, providing the industry's leading process technology and the foundry segment's largest portfolio of process-proven libraries, IPs, design tools and reference flows. The Company's owned capacity in 2015 reached above 9 million (12-inch equivalent) wafers, including capacity from three advanced 12-inch GIGAFAB™ facilities, four eight-inch fabs, one six-inch fab, as well as TSMC's wholly owned subsidiaries, WaferTech and TSMC China. TSMC is the first foundry to provide 20nm and 16nm production capabilities. TSMC's corporate headquarters are in Hsinchu, Taiwan. For more information about TSMC please visit http://www.tsmc.com.

About MediaTek

Since 1997, MediaTek has been a pioneering fabless semiconductor company and a market leader in cutting-edge systems-on-chip (SoC) for mobile devices, wireless networking, HDTV, DVD and Blu-ray. Our tightly-integrated, innovative chip designs help manufacturers optimize supply chains, reduce the development time of new products, and extend a competitive edge in crowded markets. Through MediaTek Labs, the company is also building a developer hub that will support device creation, application development, and services for the Internet of Things era. By building technologies that help connect individuals to the world around them, MediaTek is enabling people to expand their horizons and more easily achieve their goals. We believe anyone can achieve something amazing. And we believe they can do it every single day. We call this idea Everyday Genius and it drives everything we do. Visit mediatek.com for more information.

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